

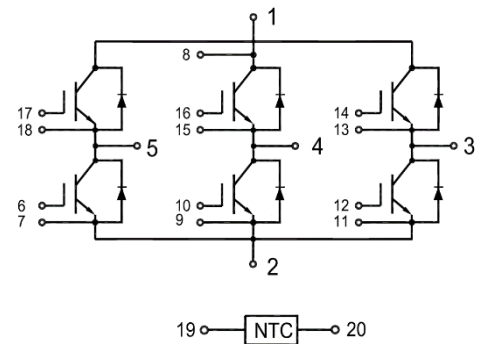


GT200FF120A8H

IGBT Module

Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated >10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested(2xIc)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



Applications:

- High Power Converters
- UPS Systems
- Motor Drives

IGBT, Inverter

Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _C	Continuous Collector Current	T _C =100°C	200	A
		T _C =25°C	400	A
I _{CM}	Repetitive Peak Collector Current	t _p =1ms	400	A
P _D	Maximum Power Dissipation per IGBT	T _C =25°C T _{Jmax} =175°C	1260	W



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=7.6\text{mA}$, $V_{CE}=V_{GE}$, $T_J=25^\circ\text{C}$	5.0	5.9	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=200\text{A}$, $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.65	2.10	V
			$T_J=125^\circ\text{C}$	2.00		V
			$T_J=150^\circ\text{C}$	2.00		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$, $V_{CE}=V_{CES}$, $T_J=25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_J=25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$		23.44		nF
C_{oes}	Output Capacitance			3.05		nF
C_{res}	Reverse Transfer Capacitance			0.26		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Gon}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	488		ns	
			$T_J=125^\circ\text{C}$	508			
			$T_J=150^\circ\text{C}$	515			
t_r	Rise Time		$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Goff}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	117		ns
				$T_J=125^\circ\text{C}$	134		
				$T_J=150^\circ\text{C}$	136		
$t_{d(off)}$	Turn-off Delay Time	$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Goff}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load		$T_J=25^\circ\text{C}$	444		ns
				$T_J=125^\circ\text{C}$	474		
				$T_J=150^\circ\text{C}$	480		
t_f	Fall Time		$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Goff}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	176		ns
				$T_J=125^\circ\text{C}$	213		
				$T_J=150^\circ\text{C}$	217		
E_{on}	Turn-on Switching Loss	$V_{CC}=600\text{V}$, $I_C=200\text{A}$, $R_{Gon}=4.7\Omega$, $V_{GE}=\pm 15\text{V}$, $di/dt=1204\text{A}/\mu\text{s}$ ($T_J=150^\circ\text{C}$) Inductive Load		$T_J=25^\circ\text{C}$	16.0		mJ
				$T_J=125^\circ\text{C}$	22.9		
				$T_J=150^\circ\text{C}$	27.2		



E _{off}	Turn-off Switching Loss	V _{CC} =600V, I _C =200A, R _{Goff} =4.7Ω, V _{GE} =±15V, du/dt=3656V/μs (T _J =150°C) Inductive Load	T _J =25°C	10.1	mJ
			T _J =125°C	15.7	
			T _J =150°C	17.4	
Q _g	Total Gate Charge	V _{GE} =+15V...-15V	T _J =25°C	1.56	μC
R _g	Internal Gate Resistance		T _J =25°C	2.9	Ω
RBSOA	I _C =400A, V _{CC} =1050V, V _p =1200V, R _{Goff} =4.7Ω, V _{GE} =+15V to 0V, T _J =150°C			Trapezoid	
SC Data	V _{CC} =600V, t _p =10μs, R _{Gon} =4.7Ω, R _{Goff} =4.7Ω, V _{GE} =±15V, T _J =125°C			1100	A
R _{θJC}	IGBT Thermal Resistance: Junction-To-Case (per IGBT)			0.119	°C/W

Diode, Reverse

Maximum Rated Values of Diode (T_C=25°C unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
I _F	Diode Continuous Forward Current	200	A
I _{FM}	Diode Maximum Forward Current	400	A

Electrical Characteristics of Diode (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
V _{FM}	Forward Voltage	I _F =200A	T _J =25°C	1.65		V
			T _J =125°C	1.75		
			T _J =150°C	1.70		
t _{rr}	Reverse Recovery Time	I _F =200A, -diF/dt=1635A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C	223		ns
			T _J =125°C	450		
			T _J =150°C	523		
I _{rr}	Peak Reverse Recovery Current	I _F =200A, -diF/dt=1635A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C	119		A
			T _J =125°C	144		
			T _J =150°C	150		



Q _{rr}	Reverse Recovery Charge	I _F =200A, -diF/dt=1635A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C	15.95	μC
			T _J =125°C	32.36	
			T _J =150°C	37.32	
E _{rec}	Reverse Recovery Energy		T _J =25°C	5.3	mJ
			T _J =125°C	11.5	
			T _J =150°C	13.0	
R _{θJC}	Diode Thermal Resistance: Junction-To-Case (per Diode)			0.193	°C/W

Internal NTC-Thermistor Characteristics

R ₂₅	T _C =25°C	5		kΩ
ΔR/R	T _C =100°C, R ₁₀₀ =465Ω		±5	%
P ₂₅	T _C =25°C	10		mW
B _{25/50}	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$	3380		K
B _{25/80}	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$	3440		K
B _{25/100}	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$	3545		K

Module

Symbol	Description	Min.	Typ.	Max.	Units
V _{ISO}	Isolation Voltage (All Terminals Shorted)	f=50Hz, 30S	4500		V
Internal Isolation		Al ₂ O ₃			
T _J	Maximum Junction Temperature			175	°C
T _{JOP}	Maximum Operating Junction Temperature Range	-40		+150	°C
T _{stg}	Storage Temperature	-40		+150	°C
CTI	Comparative Tracking Index	200			
R _{θCS}	Case-to-Sink Thermally (Conductive Grease Applied)			0.03	°C/W
M	Power Terminals Screw:M6	3.0		6.0	N·m
M	Mounting Screw:M5	3.0		6.0	N·m
G	Weight		390		g



Ordering Information Table

Device code	G	T	200	FF	120	A8	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Field Stop Trench Gate IGBT
- ③ - Rated Current (200=200A)
- ④ - Circuit Configuration (FF=Full Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

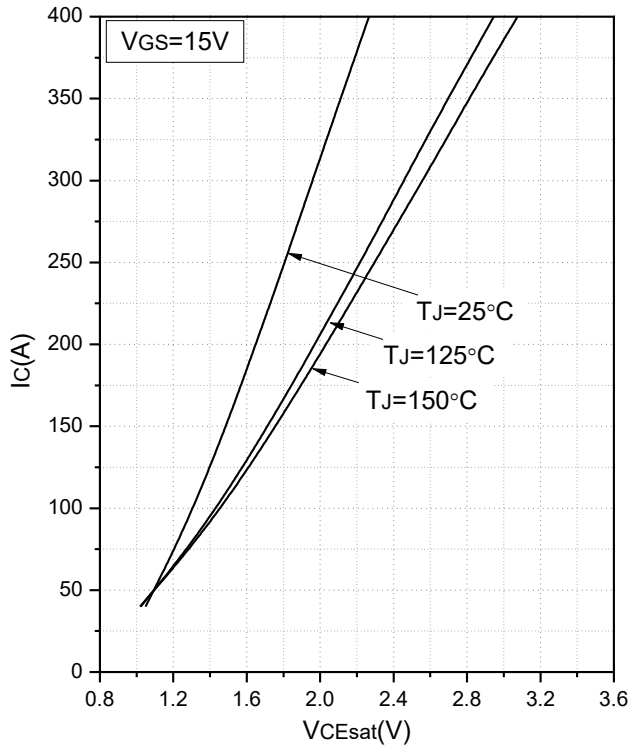


Fig.1 Typical Saturation Voltage Characteristics

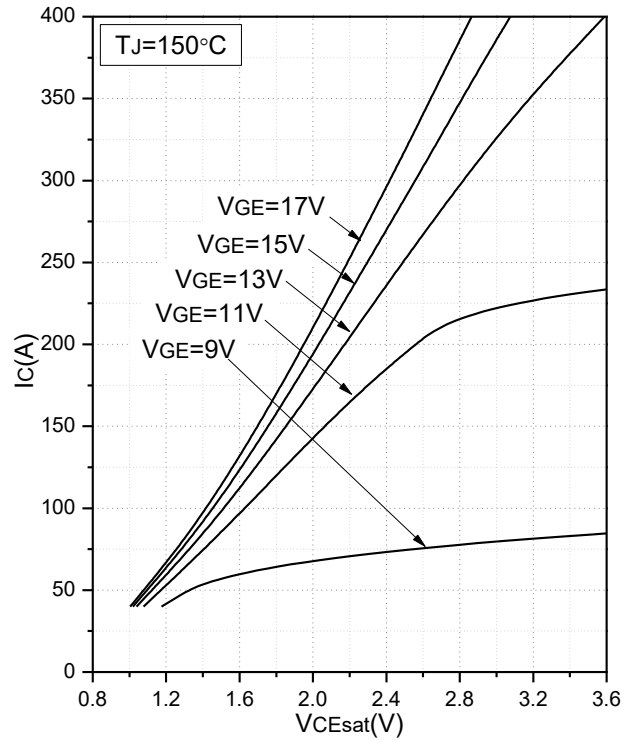


Fig.2 Typical Output Characteristics

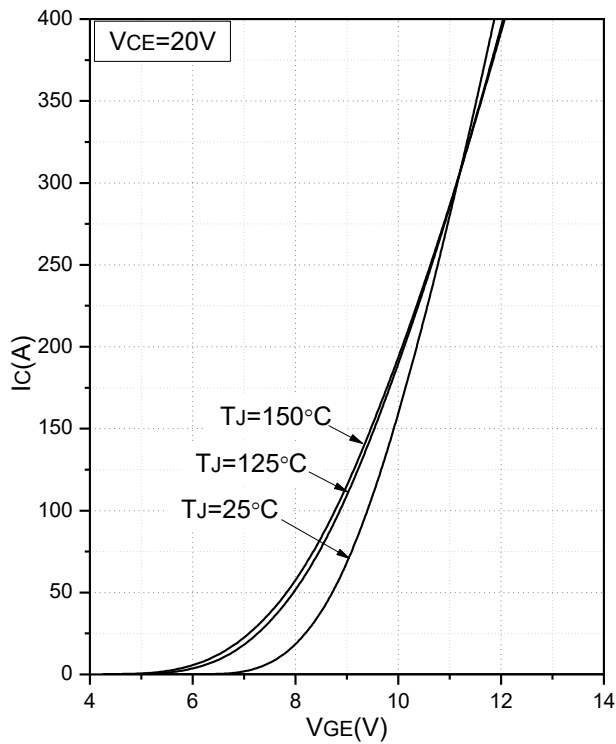


Fig.3 Transfer Characteristic

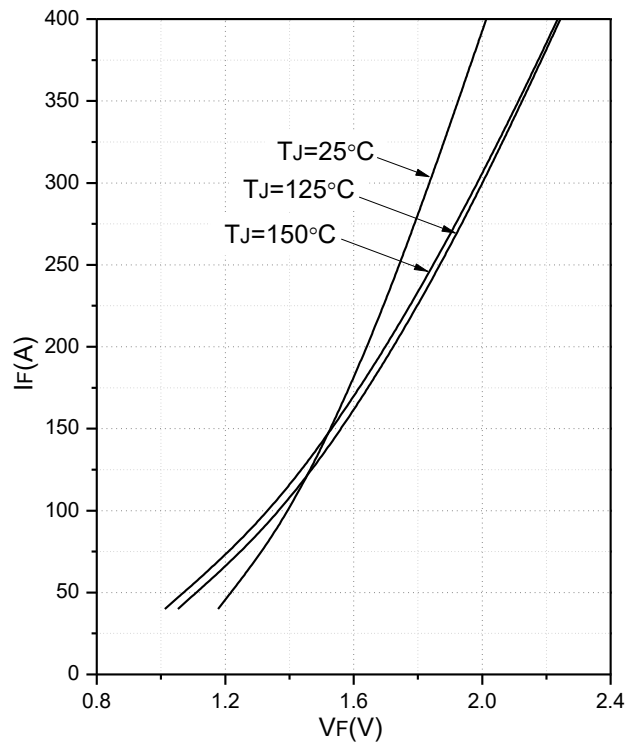


Fig.4 Forward Characteristics of Diode

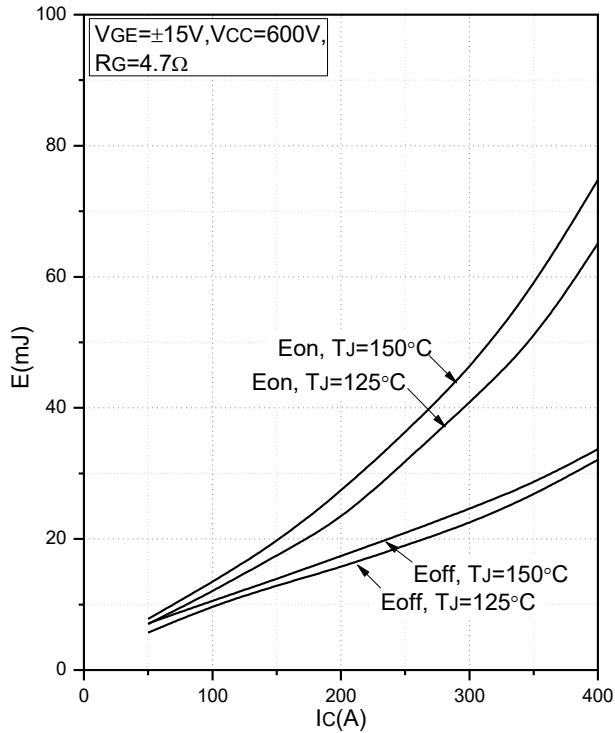


Fig.5 Typical Switching Loss vs. Collector Current

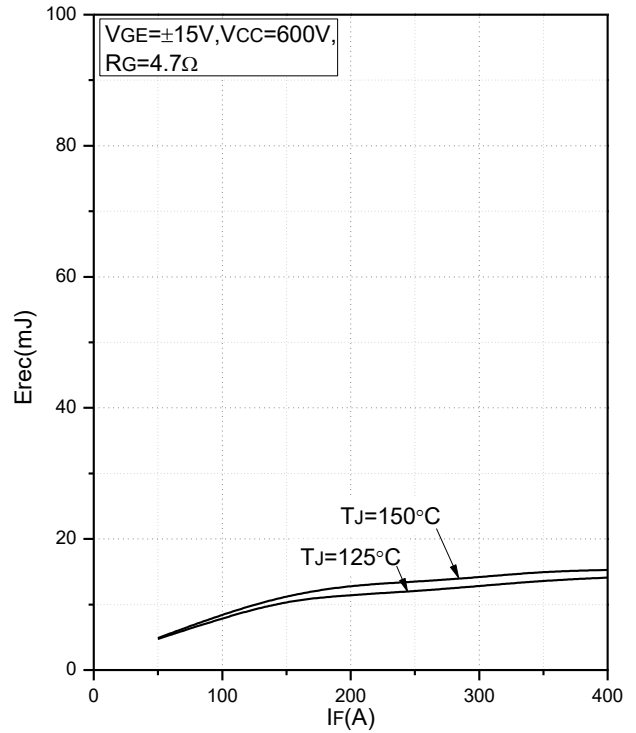


Fig.6 Typical Switching Loss vs. Forward Current

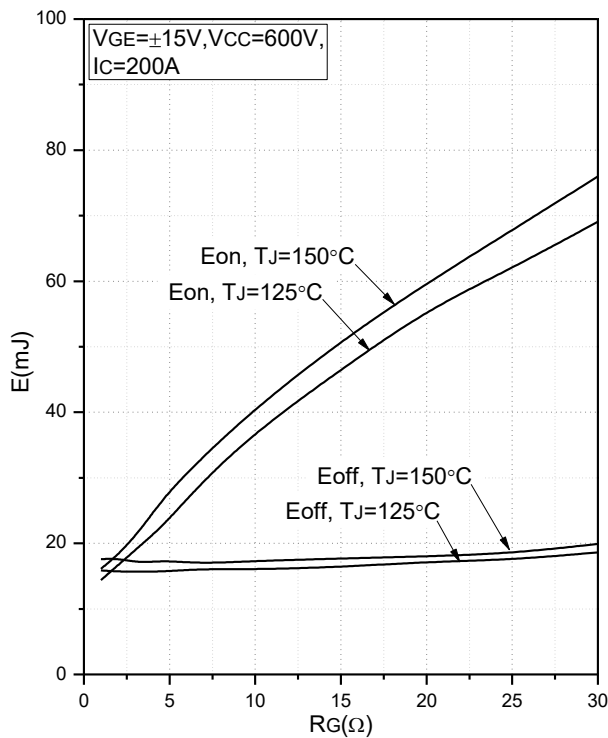


Fig.7 Typical Switching Loss vs. Gate Resistance

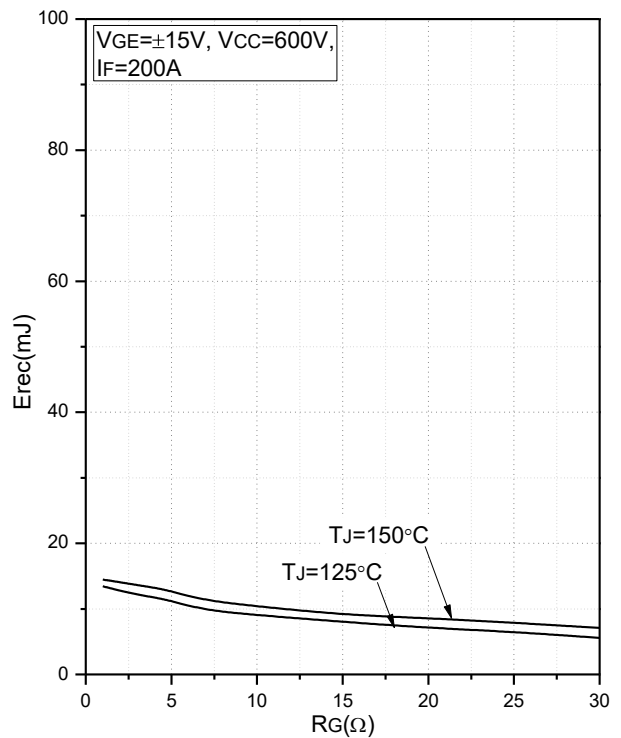


Fig.8 Typical Switching Loss vs. Gate Resistance

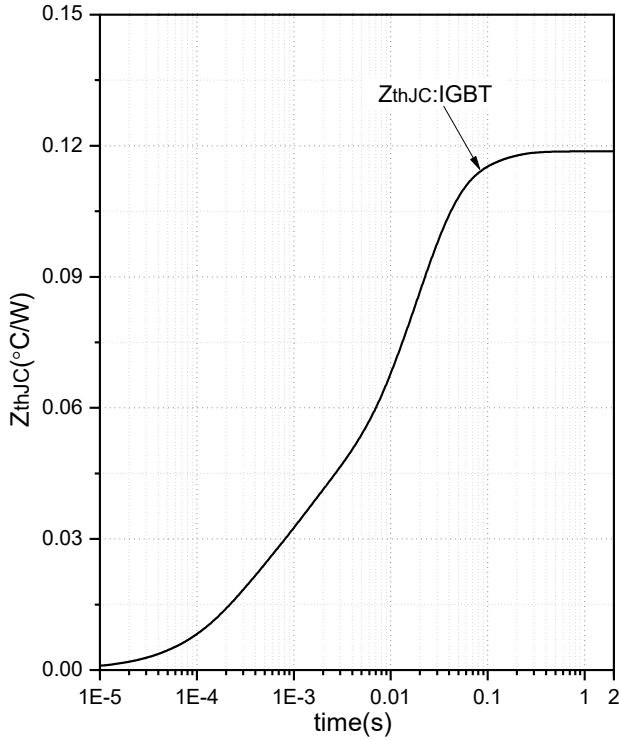


Fig.9 Transient Thermal Impedance (IGBT)

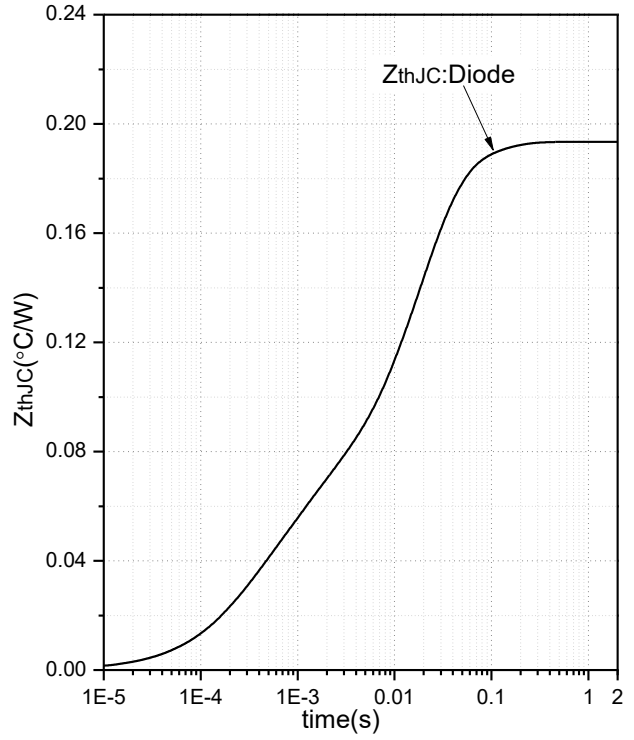


Fig.10 Transient Thermal Impedance (Diode)

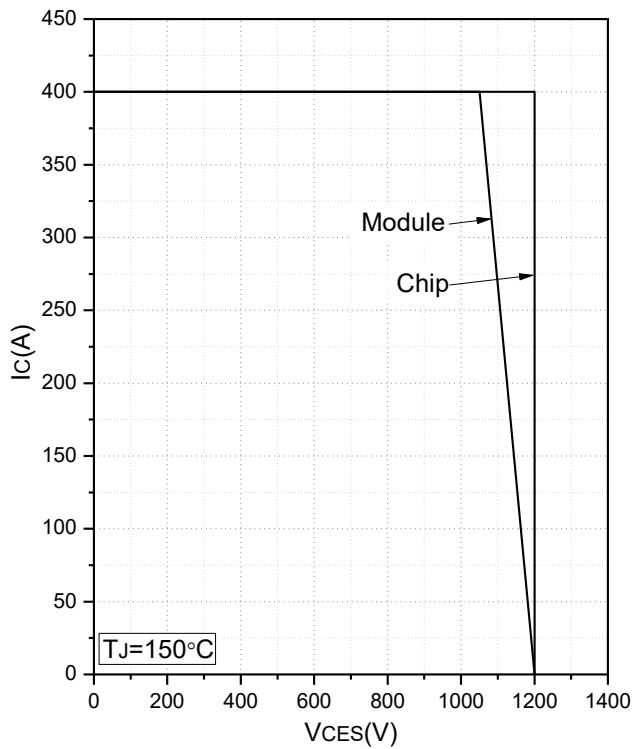


Fig.11 Reverse Bias Safe Operation Area (RBSOA)

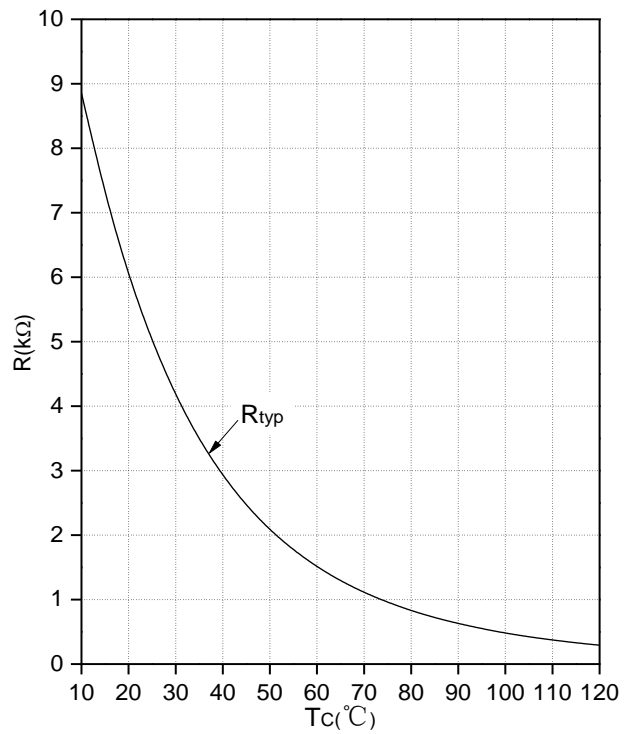


Fig.12 NTC Temperature Characteristics

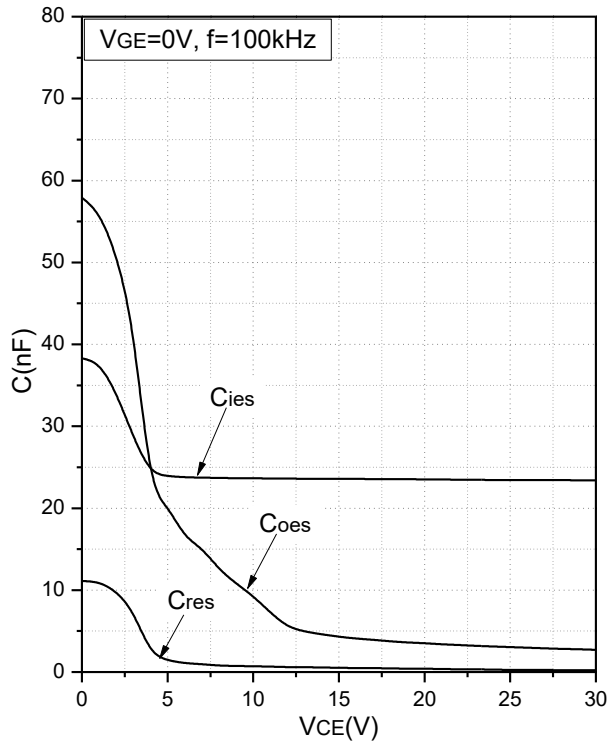
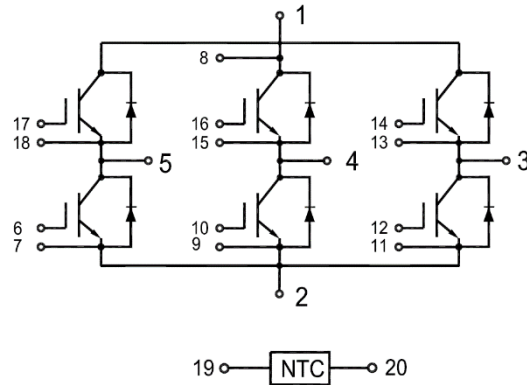


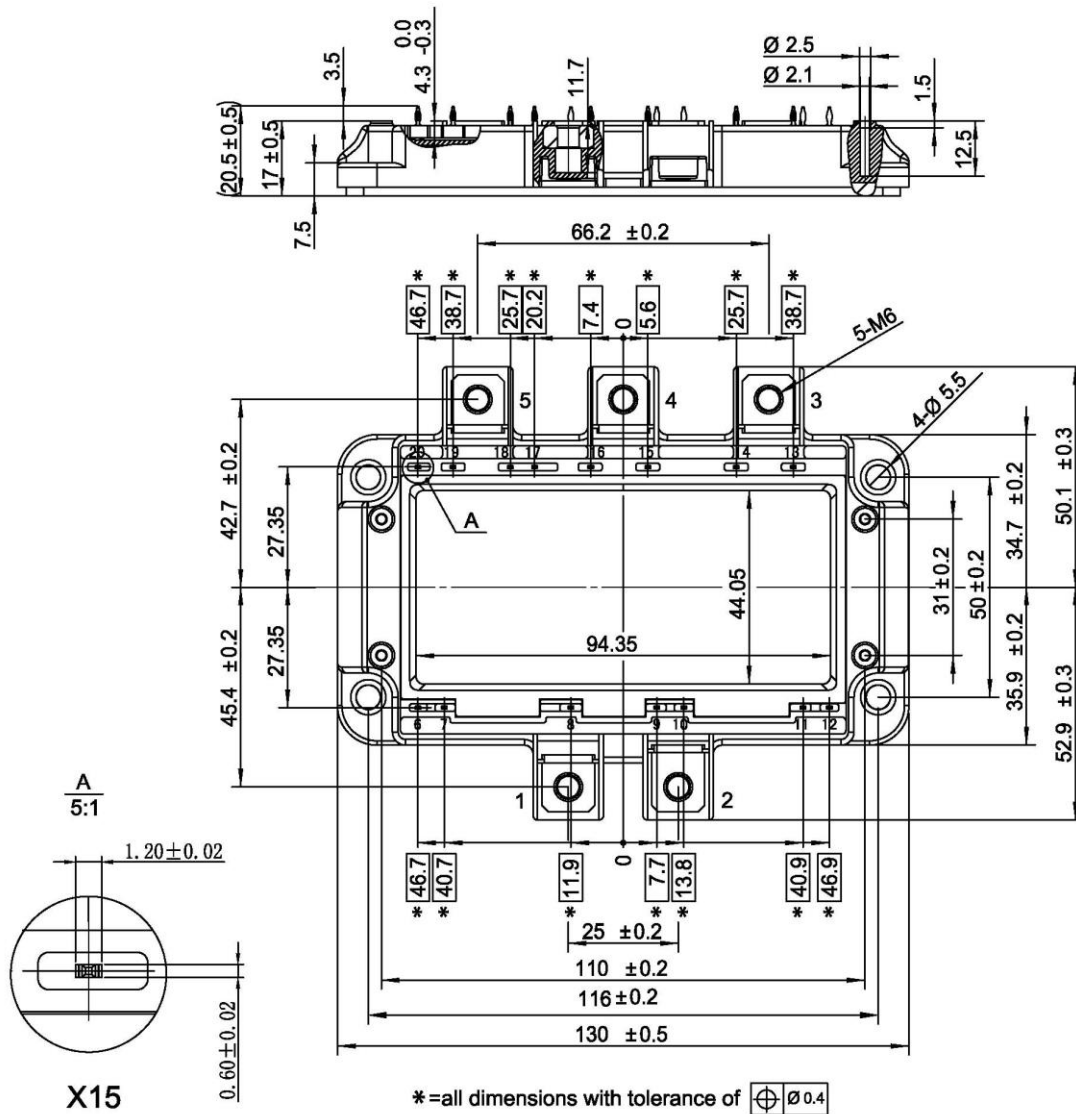
Fig.13 Capacitance Characteristics



Internal Circuit



Package Outline (Unit: mm):





Date	Revision	Notes
03/01/2024	01	Initial Release
03/13/2024	02	Add Value " $R_{g \text{ Internal}}$ "
04/01/2024	A	Updated Electrical Performance Parameters

Announcement

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